

Amendments to the Specification:

After the title and before the first line, please add the following new paragraph:

--This application claims the benefit of Japanese Application 2003-044993, filed February 21, 2003, the entirety of which is incorporated herein by reference.--

Please replace the paragraph beginning at page 3, line 2 with the following amended paragraph:

According to the present invention, there is provided a heat spreader module comprising at least a heat spreader member and an insulating substrate which are joined on a base; wherein the base includes a copper alloy which has a proof stress of not less than 45 MPa and a coefficient of thermal conductivity of not less than 270 W/mK ~~after performing~~ when subjected to a heat treatment between 600° and 900° C for 10 minutes (e.g., at 830°C for 10 minutes.

Please replace the paragraph beginning at page 4, line 24 with the following amended paragraph:

In relation to the heat spreader module constructed as described above, it is preferable that the copper alloy of the base is any one of:

- (a) a copper alloy comprising 0.1 to 1.5 mass % Cr and the balance being Cu;
- (b) a copper alloy comprising 0.1 to 0.5 mass % Zr and the balance being Cu;
- (c) a copper alloy comprising 0.05 to 0.3 mass % Zr, 0.3 to 1.2 mass % Cr, and the balance being Cu;
- (d) a copper alloy comprising 0.01 to 1.5 mass % Ag and the balance being Cu;

(e) a copper alloy comprising 1.4 to 3.0 mass % Fe, 0.05 to 0.2 mass % Zn, 0.01 to 0.1 mass % P, and the balance being Cu; and

(f) alumina-dispersed copper (e.g., copper or copper alloy having alumina particles dispersed in it).